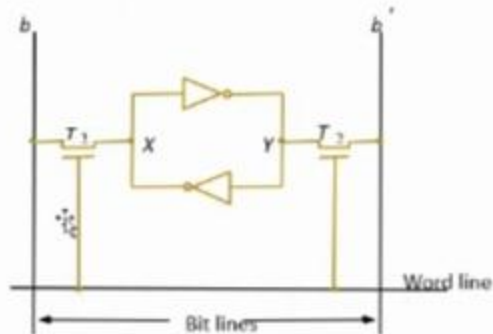


# SRAM Cell

- Two transistor inverters are cross connected to implement a basic flip-flop.
- The cell is connected to one word line and two bits lines by transistors  $T_1$  and  $T_2$
- When word line is at ground level, the transistors are turned off and the latch retains its state
- Read operation: In order to read state of SRAM cell, the word line is activated to close switches  $T_1$  and  $T_2$ . Sense/Write circuits at the bottom monitor the state of  $b$  and  $b'$



### BASIC CONCEPTS

- Maximum size of memory that can be used in any computer is determined by addressing mode.

Address	Memory Locations
16 Bit	$2^{16} = 64 \text{ K}$
32 Bit	$2^{32} = 4\text{G (Giga)}$
40 Bit	$2^{40} = 1\text{T (Tera)}$

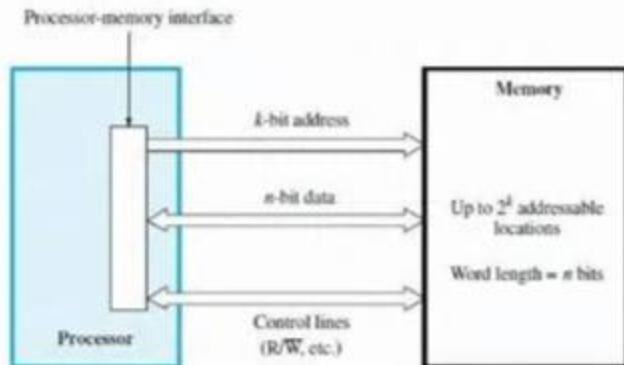


Figure 8.1 Connection of the memory to the processor.

- If MAR is  $k$ -bits long then  
→ memory may contain upto  $2^k$  addressable-locations
- If MDR is  $n$ -bits long, then  
→  $n$ -bits of data are transferred between the memory and processor.
- The data-transfer takes place over the processor-bus (Figure 8.1).
- The processor-bus has
  - 1) Address-Line
  - 2) Data-line &
  - 3) Control-Line (R/W\*, MFC - Memory Function Completed).
- The Control-Line is used for coordinating data-transfer.
- The processor reads the data from the memory by  
→ loading the address of the required memory location into MAR and



X

5V



### Read Operation

- To read the state of the cell, the word-line is activated to close switches  $T_1$  and  $T_2$ .
- If the cell is in state 1, the signal on bit-line  $b$  is high and the signal on the bit-line  $b'$  is low.
- Thus,  $b$  and  $b'$  are complement of each other.
- Sense/Write circuit
  - monitors the state of  $b$  &  $b'$  and
  - sets the output accordingly.

### Write Operation

- The state of the cell is set by
  - placing the appropriate value on bit-line  $b$  and its complement on  $b'$  and
  - then activating the word-line. This forces the cell into the corresponding state.
- The required signal on the bit-lines is generated by Sense/Write circuit.

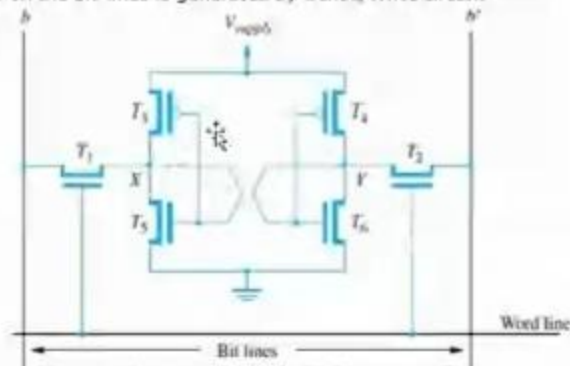
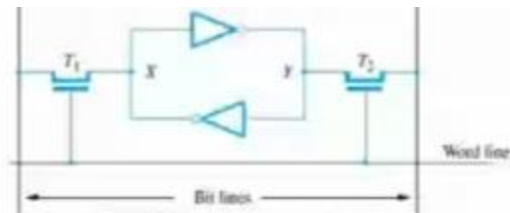


Figure 8.5 An example of a CMOS memory cell.

### CMOS Cell

- Transistor pairs  $(T_3, T_5)$  and  $(T_4, T_6)$  form the inverters in the latch (Figure 8.5).
- In state 1, the voltage at point  $X$  is high by having  $T_5, T_6$  ON and  $T_4, T_3$  are OFF.
- Thus,  $T_1$  and  $T_2$  returned ON (Closed), bit-line  $b$  and  $b'$  will have high and low signals respectively.
- **Advantages:**
  - 1) It has low power consumption as the current flows in the cell only when the cell is active.
  - 2) Static RAM's can be accessed quickly. Its access time is few nanoseconds.
- **Disadvantage:** SRAMs are said to be volatile memories as their contents are lost when power is interrupted.



**Figure 8.4** A static RAM cell.

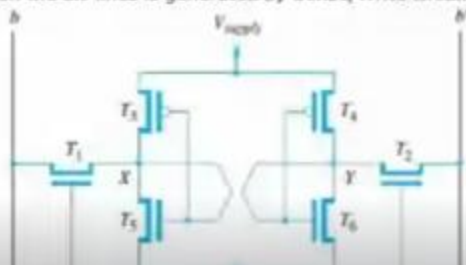
- Two inverters are cross connected to form a latch (Figure 8.4).
- The latch is connected to 2-bit-lines by transistors  $T_1$  and  $T_2$ .
- The transistors act as switches that can be opened/closed under the control of the word-line.
- When the word-line is at ground level, the transistors are turned off and the latch retain its state.

#### **Read Operation**

- To read the state of the cell, the word-line is activated to close switches  $T_1$  and  $T_2$ .
- If the cell is in state 1, the signal on bit-line  $b$  is high and the signal on the bit-line  $b'$  is low.
- Thus,  $b$  and  $b'$  are complement of each other.
- Sense/Write circuit
  - monitors the state of  $b$  &  $b'$  and
  - sets the output accordingly.

#### **Write Operation**

- The state of the cell is set by
  - placing the appropriate value on bit-line  $b$  and its complement on  $b'$  and
  - then activating the word-line. This forces the cell into the corresponding state.
- The required signal on the bit-lines is generated by Sense/Write circuit.



## COMPUTER ORGANIZATION

### ASYNCHRONOUS DRAM

- Less expensive RAMs can be implemented if simple cells are used.
- Such cells cannot retain their state indefinitely. Hence they are called **Dynamic RAM (DRAM)**.
- The information stored in a dynamic memory-cell in the form of a charge on a capacitor.
- This charge can be maintained only for tens of milliseconds.
- The contents must be periodically refreshed by restoring this capacitor charge to its full value.

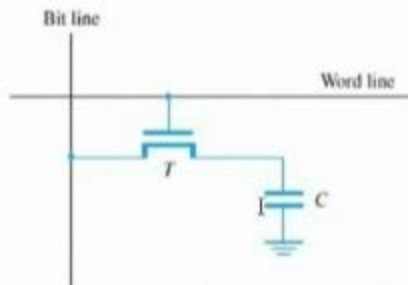


Figure 8.6 A single-transistor dynamic memory cell.

- In order to store information in the cell, the transistor T is turned „ON“ (Figure 8.6).
- The appropriate voltage is applied to the bit-line which charges the capacitor.
- After the transistor is turned off, the capacitor begins to discharge.
- Hence, info. stored in cell can be retrieved correctly before threshold value of capacitor drops down.
- During a read-operation,
  - transistor is turned „ON“
  - a sense amplifier detects whether the charge on the capacitor is above the threshold value.
    - If (charge on capacitor) > (threshold value) Bit-line will have logic value „1“.
    - If (charge on capacitor) < (threshold value) Bit-line will set to logic value „0“.

## COMPUTER ORGANIZATION

### ASYNCHRONOUS DRAM DESCRIPTION

- The 4 bit cells in each row are divided into 512 groups of 8 (Figure 5.7).
- 21 bit address is needed to access a byte in the memory. 21 bit is divided as follows:
  - 1) 12 address bits are needed to select a row.  
I.e.  $A_{20-9} \rightarrow$  specifies row-address of a byte.
  - 2) 9 bits are needed to specify a group of 8 bits in the selected row.  
I.e.  $A_{8-0} \rightarrow$  specifies column-address of a byte.

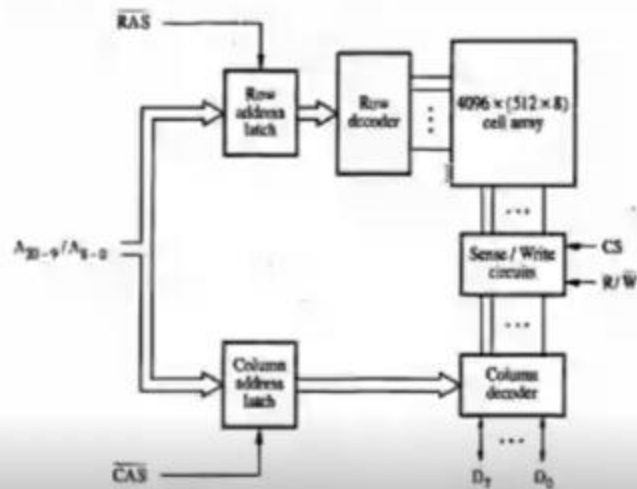


Figure 5.7 Internal organization of a 2M x 8 dynamic memory chip